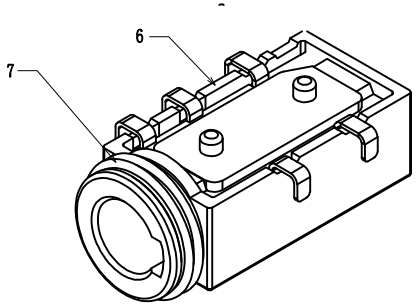
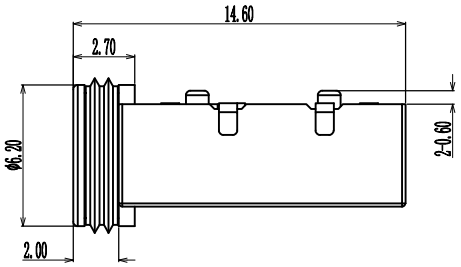
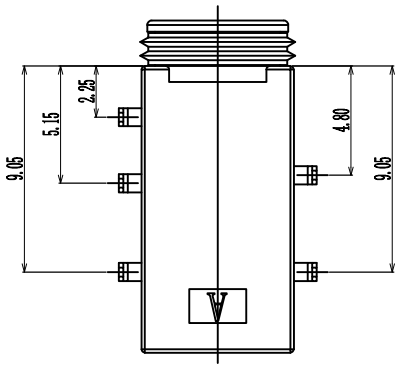
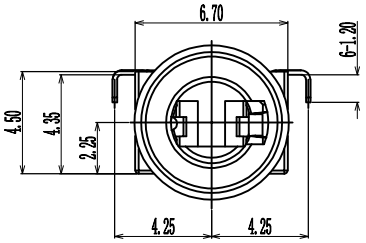
RoHS Compliant

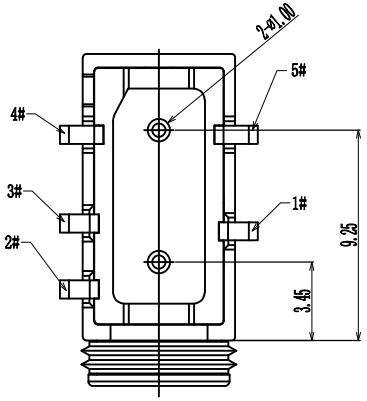


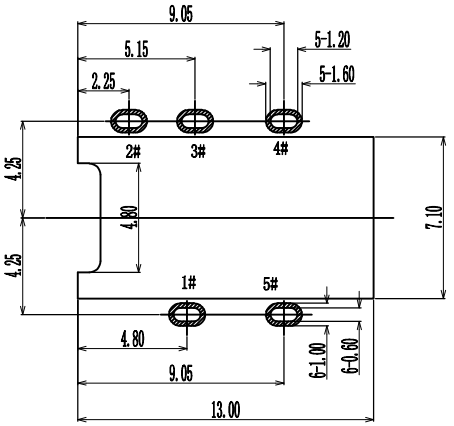
3D VIEW







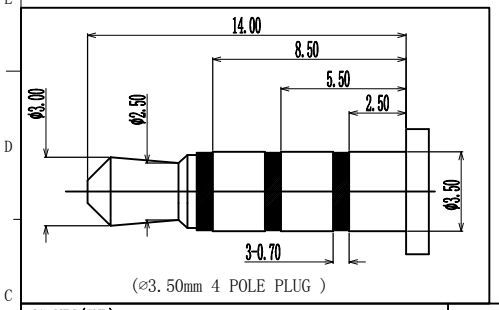




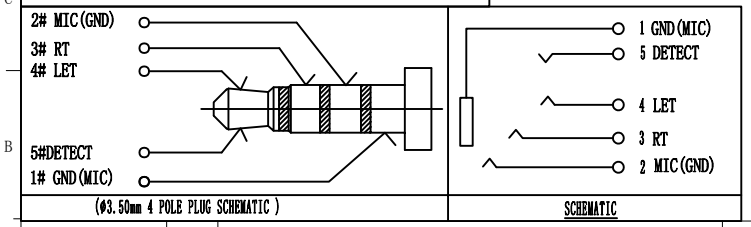
P.C.B LAYOUT

TOP VIEW

1. CONTACT CURRENT RATING: 1A.
2. CONTACT RESISTANCE: 100 mΩ MAX.;
3. INSULATION RESISTANCE: 100MΩ MIN.;
4. DIELECTRIC WITHSTANDING: 500V AC MIN.;
5. DURABILITY: 5,000 CYCLES MIN.;
6. CONNECTOR MATING FORCES: 30N MAX.;
7. CONNECTOR UNMATING FORCES: 3N MIN.;
8. TERPROOF LEVEL: IP67;



(⌀3.50mm 4 POLE PLUG)



(Φ3.50mm 4 POLE PLUG SCHEMATIC) | SCHEMATIC

NO.	DESCRIPTION	MATERIAL	REMARKS	QTY
7	WATERPROOF RING	SILICA GEL		1
6	HOUSING	HIGH TEMPERATURE PLASTIC MATERIALE; COLOR BLACK		1
5	TERMINAL 5#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm	1
4	TERMINAL 4#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm	1
3	TERMINAL 3#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm	1
2	TERMINAL 2#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm	1
1	TERMINAL 1#	STAINLESS STEEL; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm	1

UNLESS OTHERWISE, GENERAL TOLERANCE:

X.xxx	±0.10
X.xx	±0.20
X.x	±0.30
X.	±0.50

ANGULAR:

X.xx	±1°
X.x	±3°
X.	±5°

WFDCONN 深圳市旺富达电子有限公司 Shenzhen WFD Electronics Co.Ltd..

TITLE: ø3.5 WATERPROOF PHONE JACK CONNECTOR

P/N: MPJ-05C62-05-G-022

MODEL:

DRAW NO.:

THIRD ANGLE PROJECTION | UNIT: mm | SCALE: 1:1 | SIZE: A4 | SHEET: 1/1

N/A	A	NEW DRAWING	2017.10.08	Liu Miao
ECN NO.	REV.	DESCRIPTION	DATE	CHANGE

DESIGN	Liu Miao	2017.10.08
CHECK	SIMON	2017.10.08
APPROVAL	DAVID	2017.10.08